Claims

1. A solder coated material comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability provided on the substrate as base plating and having a thickness of 0.5 - 5 micrometers, and a hot dip solder plating layer provided on the electroplated layer and having a thickness of 10 - 50 micrometers.

2. A solder coated material as claimed in claim 1 characterized in that the difficult to solder material is an iron-nickel alloy.

3. A solder coated material as claimed in claim 1 or claim 2 characterized in that the material having excellent solderability is any one of gold, silver, copper, tin, nickel, and solder alloys.

4. A solder coated material as claimed in claim 3 characterized in that the material having excellent solderability is a tin-silver alloy.

5. A portion to be soldered of an electronic part having an electroplated layer of a material having excellent solderability and having a thickness of 0.5 - 5 micrometers applied as base plating atop a substrate comprising a difficult to solder

material, and a hot dip solder plating layer with a thickness of 10 - 50 micrometers applied atop the electroplated layer.

6. A portion to be soldered of an electronic part as claimed in claim 5 characterized in that the difficult to solder material is an iron-nickel alloy.

7. A portion to be soldered of an electronic part as claimed in claim 5 characterized in that the material having excellent solderability is any one of gold, silver, copper, tin, nickel, and solder alloys.

8. A portion to be soldered of an electronic part as claimed in claim 7 characterized in that the material having excellent solderability is a solder alloy of a tin-silver alloy.

9. A portion to be soldered of an electronic part as claimed in any one of claims 5 - 8 characterized in that the portion to be soldered of an electronic part is a lead frame for an electronic part, a lid of a packaged electronic part, a battery terminal, a shield of a module, or a connector for a surface mounted part.

10. A manufacturing method for a solder coated material characterized by performing electroplating on necessary locations of a difficult to solder material with a material having excellent solderability, and then passing the difficult to solder

material through a molten solder bath and adhering molten solder to the electroplated locations.

11. A manufacturing method for a solder coated material as claimed in claim 10 characterized in that ultrasonic waves are applied to the molten solder bath.

12. A manufacturing method for a solder coated material as claimed in claim 10 characterized in that the difficult to solder material is an iron-nickel alloy.

13. A manufacturing method for a solder coated material as claimed in claim 10 characterized in that the material having excellent solderability is any one of gold, silver, copper, tin, nickel, and solder alloys.

14. A manufacturing method for a solder coated material as claimed in any one of claims 10 - 13 characterized in that the molten solder bath is maintained in an inert atmosphere.

15. A manufacturing method for a solder coated material as claimed in any one of claims 10 - 13 characterized in that the molten solder bath in the molten solder is a molten solder bath which is spouting.

Add A'

add B'

Add C'